Panel: Test and Reliability Challenges in Automotive Microelectronics

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Abstract

Absolutely fail-safe operation in any critical situation, highest reliability in day-to-day operation and best-in-class convenience at a reasonable price: all drive innovation in automotive electronics. These goals result in car systems with ever-increasing complexity, challenging every single component, IC and line of code. As electronics’ failure rates are perceived to grow, we introduce root cause analysis, key technologies and new measures that enable carmakers to keep pace. The goal is to introduce test and reliability challenges and respective solutions for automotive systems. Representatives of car companies and suppliers will explain their views and practical experiences.